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SEL-REX CORPORATION, Nutley, New Jersey

Copies of Patents may be obtained by writing to Commissioner of Patents, Washington, D. C. Price 50 cents each.

3,396,042, 8/68—ELECTROLESS GOLD—R. Duva to Sel-Rex Corp. An aqueous solution containing a soluble gold cyanide compound, a soluble palladous salt and an alkali to provide a *p*H value between 8.0–11.0, wherein a controlled ratio of CN^-/Pd^{++} is maintained to induce the chemical deposition of gold on a conductive surface.

3,396,091, 8/68—ELECTRODE—E. H. Lyons and R. M. Dempsey to General Electric Co. A process of plating a platinum metal onto an electrode from essentially an alkali metal or alkaline earth metal halide bath.

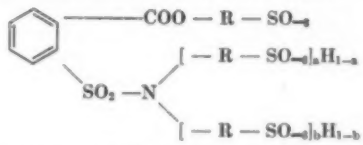
3,396,092, 8/68—PLATING METHOD—R. C. Mayer and C. D. Stricken to U. S. Steel Corp. A method of electroplating a partially coated metallic substrate in an acidic electrolyte by applying a holding voltage potential which is above the decomposition potential of the electrolyte prior to immersing the workpiece into the bath.

3,397,125, 8/68—ELECTROLYTIC PROCESSES—J. G. Tapley to Imperial Chemical Industries Ltd. A process for refining metals from the group of copper, silver, gold, zinc and cobalt by electrodepositing onto a surface containing a conducting silicone elastomer. The metal so deposited may be easily stripped from the electrode without contaminating the metal with parts of the electrode and without damage to the electrode.

3,397,126, 8/68—BULK PLATING—F. M. Gilbert to Sel-Rex Corp. An apparatus for plating small parts by a vibratory means is disclosed.

3,397,127, 8/68—GOLD PLATING—E. K. Camp to American Chemical and Refining Co. Inc. A method of plating gold wherein a soluble gold cyanide complex salt is dissolved in water and the resultant solution acidified to a *p*H of about 2.0–5.0 to expel substantially all free cyanide therefrom. The *p*H of the solution is then raised to a value of about 6.1 to 10.5; the resultant electroplate is characterized by having a low edge-to-center thickness ratio.

3,309,123, 8/68—BRIGHT NICKEL PLATING BATH—F. Passal to M&T Chemicals Inc. An aqueous acidic nickel plating bath containing at least one nickel compound, a primary brightener a compound containing an ion of the structure:



wherein a and b are each integers 0–1 and R is a hydro-carbon-di-yl moriety which contains at least two carbon atoms.

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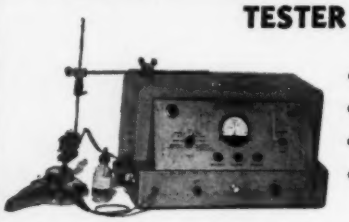

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